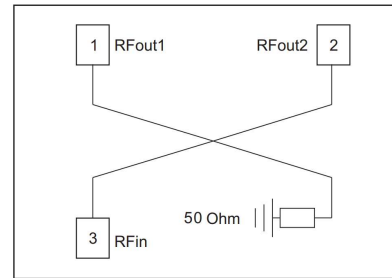


Performance

- Frequency: 2.4~3.6GHz
- Insertion loss: 0.6dB
- Chip size: 1.25*0.85*0.1mm

Function Diagram

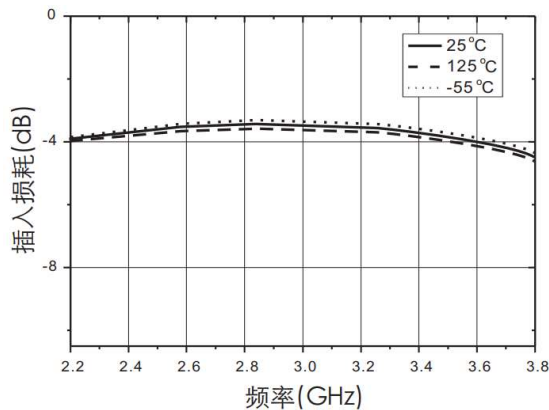


Electrical Specifications (Ta=+25°C, 50Ω system)

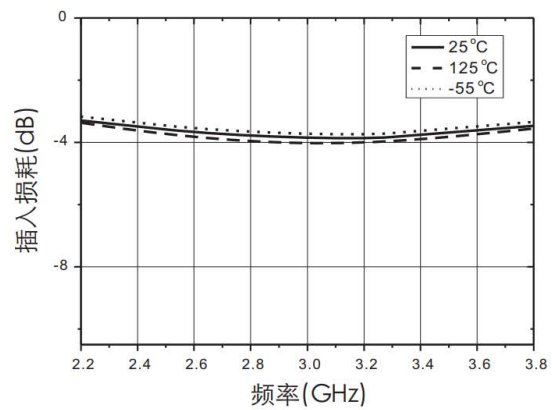
Parameter	Min	Typical	Max	Unit
Frequency Range	2.4~3.6			GHz
Insertion Loss	-	0.6	-	dB
Input Return loss	18	25	-	dB
Output Return loss	15	17	-	dB
Isolation	20	23	-	dB
Amplitude Balance	-	±0.3	-	dB
Phase Balance	-	±3.0	-	Deg

Test Curves (Die chip + Bonding line test)

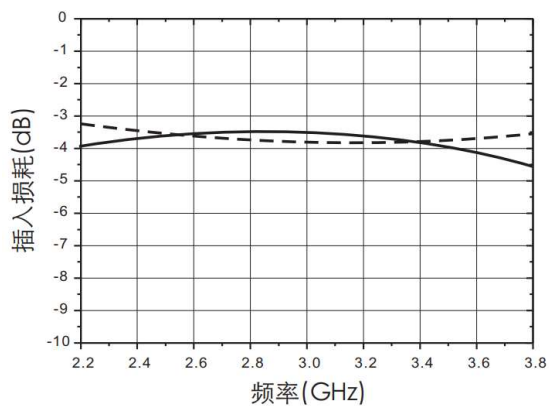
Insertion loss vs. Freq



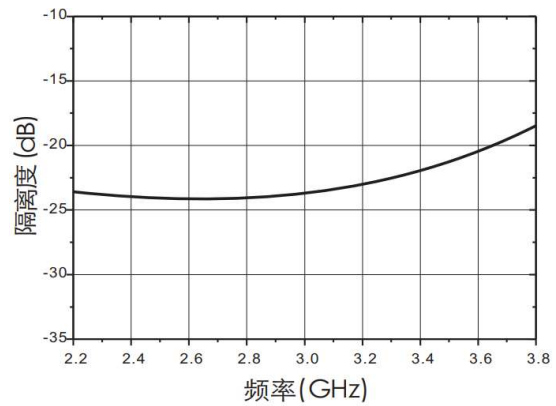
Insertion loss vs. Freq



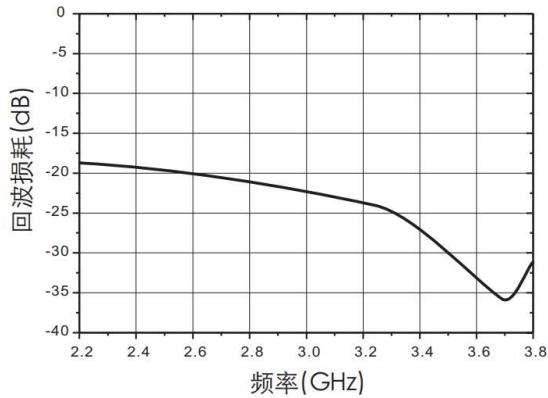
Insertion loss vs. Freq



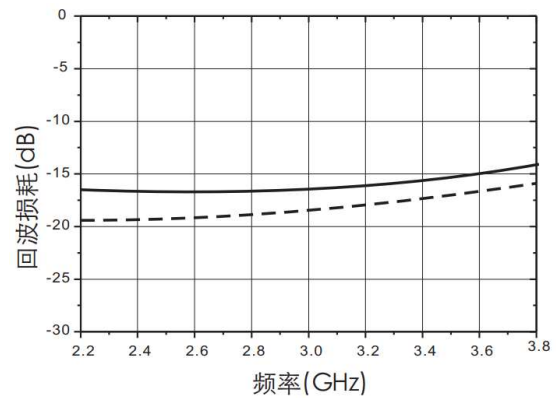
Isolation vs. Freq



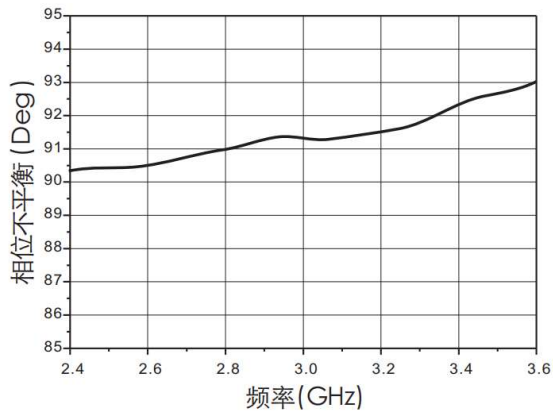
Input Return loss vs. Freq



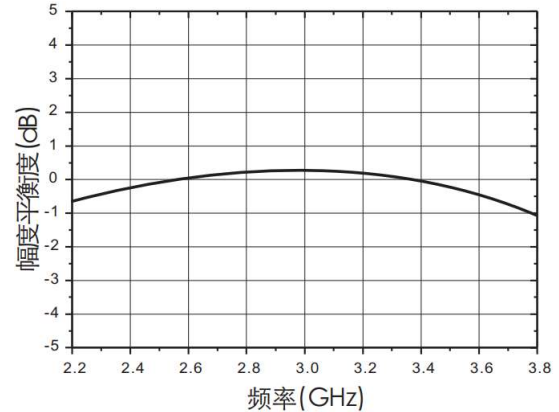
Output Return loss vs. Freq



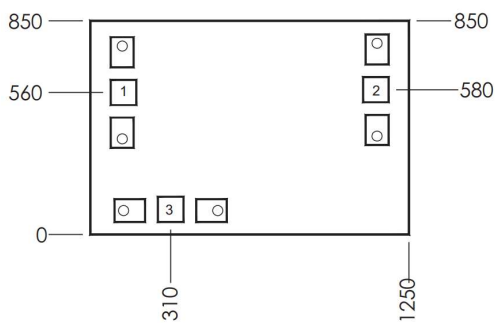
Phase Balance vs. Freq



Amplitude Balance vs. Freq



Outline Size



Note:

Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated, size: 100*100(um)
4. Don't bonding on thru holds
5. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1,2	RFout 1, RFout2	RF output port, 50ohm
3	RFin	RF input port, 50ohm
	GND	Bottom must be grounded

Absolute Max Ratings

Max Input Power	+27dBm
Static Class	Class 1A
Storage Temperature	-65 ~ +150°C
Operating Temperature	-55 ~ +125°C

Note: For high power application, assemble with Eutectic sintering.



Application

